

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of claims:

1-5. (Cancelled)

6. (Currently Amended) A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;
wherein the through-bores are approximately 20 µm in size;
through-connecting, wherein an electrically conductive general layer is built up ;
etching a strip conductor image into the electrically conductive general layer;
filling of the bores of the through-connections with a medium in the form of a lacquer, wherein the lacquer is at least partly accomplished by means of screen printing;
lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;
applying an insulating lacquer to the surfaces of the circuit board; and
producing strip conductors arranged above the through-connections;
wherein no layers are applied to the circuit board between the steps of etching and applying an insulating lacquer.

7. (Previously Presented) The method as claimed in claim 6, wherein the medium used in filling the bores and insulating lacquer is identical.

8.. (Previously Presented) The method as claimed in claim 6, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

9. (Previously Presented) The method as claimed in claim 6 wherein the strip conductors arranged above the through-connections are carbon.

10. (Previously Presented) The method as claimed in claim 6, further comprising separating individual circuit boards by means of a milling process.

11. (Cancelled)

12. (Previously Presented) The method as claimed in claim 6, wherein the insulating lacquer is an International Standard Organization lacquer.

13. (Previously Presented) A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;
wherein the through-bores are approximately 20 μm in size;
through-connecting, wherein an electrically conductive general layer is built up;
etching a strip conductor image into the electrically conductive general layer;
filling of the bores of the through-connections with a medium in the form of a lacquer, wherein the lacquer is at least partly accomplished by means of screen printing;
without brushing the electrically conductive general layer of the circuit board,
lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;
applying an insulating lacquer to the surfaces of the circuit board; and
producing strip conductors arranged above the through-connections; and

~~wherein no layers are applied to the circuit board between the steps of etching and applying an insulating lacquer.~~

14. (Previously Presented) The method as claimed in claim 13, wherein the medium used in filling the bores and insulating lacquer is identical.

15. (Previously Presented) The method as claimed in claim 13, wherein the medium used in filling the bores and the insulating lacquer is non-resistant to etching.

16. (Previously Presented) The method as claimed in claim 13, wherein the strip conductors arranged above the through-connections are carbon.

17. (Previously Presented) The method as claimed in claim 13, further comprising separating individual circuit boards by means of a milling process.

18. (Cancelled)

19. (Previously Presented) The method as claimed in claim 13, wherein the insulating lacquer is an International Standard Organization lacquer.

20-25. (Cancelled)

26. (Previously Presented) A method for the production of circuit boards comprising the following steps in the sequential order of:

drilling through-bores for establishing through-connections;
through-connecting, wherein an electrically conductive general layer is built up;
etching a strip conductor image into the electrically conductive general layer;
filling of the bores of the through-connections with a medium in the form of a lacquer, wherein the lacquer is at least partly accomplished by means of screen printing;

Applicant(s) : George Busch
Serial No. : 10/599,901
Filed : April 19, 2007
Page : 5 of 7

Attorney Docket No.: 3A001-010001

lacquering of the surfaces on which through-connections are present and, at least in the proximity of which, strip conductors are later provided;

applying an insulating lacquer to the surfaces of the circuit board; and

producing strip conductors arranged above the through-connections;

~~wherein no layers are applied to the circuit board between the steps of etching and applying an insulating lacquer.~~